

**ATTACHMENT OF ELECTRONIC DEVICE
PACKAGES TO HEAT SINKS**

ABSTRACT OF THE DISCLOSURE

A heat sink having a support base which supports a base plate is used to mount one or more device packages on a circuit board or the like. The support base is adapted to be secured to the circuit board. The base plate has opposed major faces adapted for mating with device packages. Tongues or clips secure individual device packages on
5 the major faces of the base plate independently to that device packages may be removeably attached to either or both sides of the base plate.

Figure 5